**Product data sheet** 

## 1. General description

Hyperfast power diode in a 2-lead TO247 plastic package





### 2. Features and benefits

- Low leakage current
- · Low thermal resistance
- · Low reverse recovery current
- · Reduces switching losses in associated MOSFET or IGBT

## 3. Applications

- Active PFC in air conditioner/EV charger/PV
- Continuous Current Mode (CCM) Power Factor Correction (PFC)
- · Half-bridge/full-bridge switched-mode power supplies

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes		Values		Unit	
Absolute maximum rating								
$V_{RRM}$	repetitive peak reverse voltage				600		V	
I <sub>F(AV)</sub>	average forward current	$δ = 0.5$ ; square-wave pulse; $T_{mb} \le 97$ °C; Fig. 1; Fig. 2; Fig. 3		20		А		
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 97 °C; square-wave pulse		40		A		
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; <u>Fig. 4</u>		185		А		
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse			203		Α	
Symbol	Parameter	Conditions	Notes	s Min Typ Max		Max	Unit	
Static ch	aracteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	2.10	2.60	V	
		I <sub>F</sub> = 20 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>		-	1.40	1.90	V	
Dynamic characteristics								
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}$ ; $V_R = 30 \text{ V}$ ; $dI_F/dt = 200 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7		-	16	-	ns	

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		К <b>——</b> А
2	А	anode		001aaa020
mb	mb	mounting base; connected to cathod	K A TO247-2L	

# 6. Ordering information

### Table 3. Ordering information

Type number	Package	Orderable part number	Packing	Small packing	Package	Package
	name		method	quantity	version	issue date
BYC20MW-600PT2	TO247-2L	BYC20MW-600PT2Q	Tube	30	TO247L-2L	10-Nov-2020

# 7. Marking

### Table 4. Marking codes

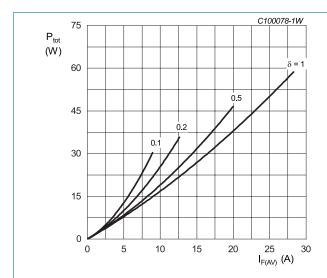
Type number	Marking codes
BYC20MW-600PT2	BYC20MW 600PT2

# 8. Limiting values

### Table 5. Limiting values

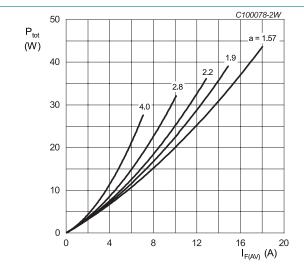
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			600	V
$V_{\text{RWM}}$	crest working reverse voltage			600	V
$V_R$	reverse voltage	DC		600	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 97 °C; Fig. 1; Fig. 2; Fig. 3		20	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 97 °C; square-wave pulse		40	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		185	A
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		203	Α
T <sub>stg</sub>	storage temperature			-65 to 175	°C
T <sub>j</sub>	junction temperature			-65 to 175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$ V<sub>o</sub> = 1.466 V; R<sub>s</sub> = 0.0216 Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor =  $I_{F(RMS)}/I_{F(AV)}$  $V_o$  = 1.466 V;  $R_s$  = 0.0216  $\Omega$ 

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

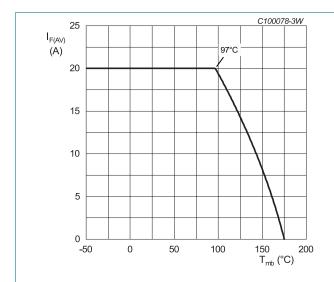


Fig. 3. Forward current as a function of mounting base temperature; maximum values

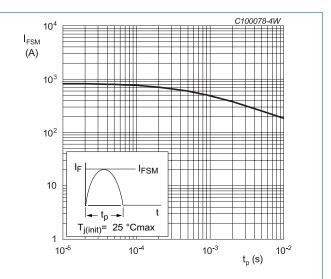


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

## 9. Thermal characteristics

#### **Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	<u>Fig. 5</u>		-	-	1.68	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W

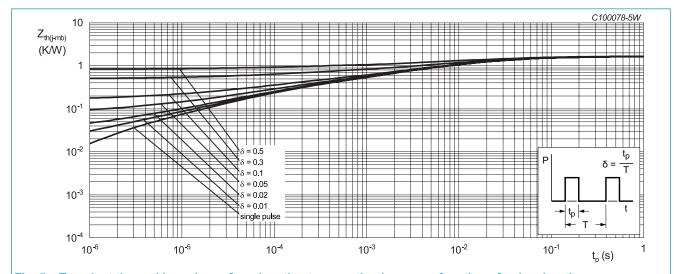
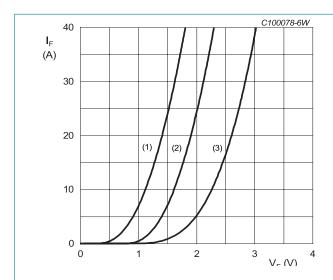


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; maximum values

# 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
$V_{F}$	forward voltage	I <sub>F</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	2.10	2.60	V
		I <sub>F</sub> = 20 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>		-	1.40	1.90	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	0.71	10	μΑ
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 150 °C		-	-	0.5	mA
Dynamic	characteristics						
Q <sub>r</sub>	reverse charge	$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	79	-	nC
		$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$		-	245	-	nC
t <sub>rr</sub> rev	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	16	-	ns
		$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_i = 25 \text{ °C}; Fig. 7$		-	28	-	ns
		$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_i = 125 \text{ °C}; Fig. 7$		-	43	-	ns
I <sub>RM</sub>	peak reverse recovery current	$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_J = 25 \text{ °C}; Fig. 7$		-	5.7	-	А
		$I_F = 20 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$		-	11.5	-	А



 $V_o$  = 1.466 V;  $R_s$  = 0.0216  $\Omega$ 

(1) T<sub>j</sub> = 150 °C; typical values (2) T<sub>i</sub> = 150 °C; maximum values

(3)  $T_i = 25$  °C; maximum values

Fig. 6. Forward current as a function of forward voltage

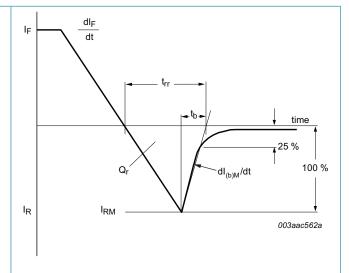
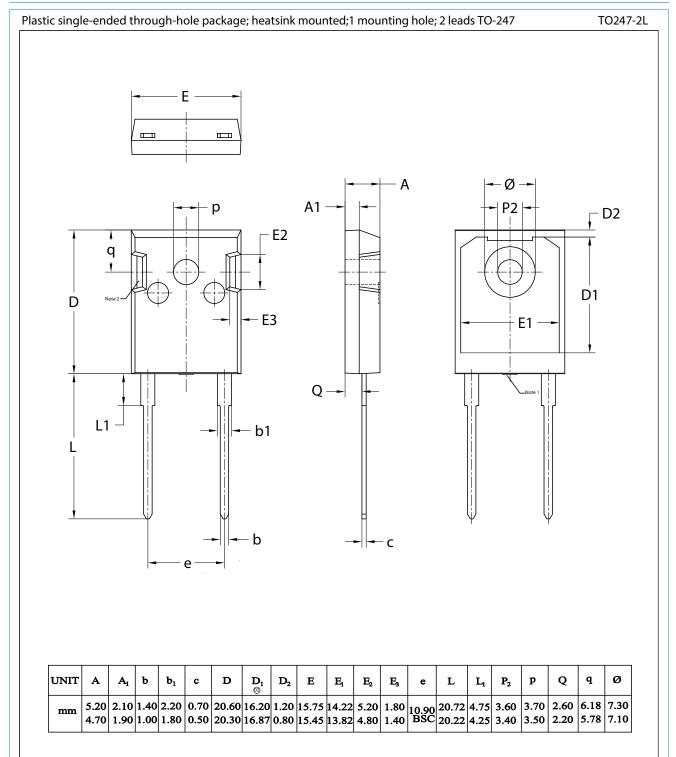


Fig. 7. Reverse recovery definitions; ramp recovery

# 11. Package outline



#### Note:

- 1. Mold resin protrusion max 0.127mm.
- 2. Metal exposed with Sn plating.

## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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